WHAT IS CLAIMED IS:

1. A sealable sheet for sealing an electronic element comprising:

a first layer and a second layer sequentially toward one side in a thickness direction, the first layer being in contact with the electronic element and the second layer being exposed outwardly when sealing the electronic element, wherein

the first layer and the second layer have thermosetting properties,

a one-side surface in the thickness direction of the second layer before thermal curing is softer than an other-side surface in the thickness direction of the first layer before thermal curing at 90°C, wherein a recessed amount D2 formed on the softer one-side surface in the thickness direction of the second layer before thermal curing is larger than a recessed amount formed on the other-side surface in the thickness direction of the first layer before thermal curing, in an iron ball drop test at 90°C, and

a ratio of a thickness T2 of the second layer to a thickness T1 of the first layer satisfies the formula of $1.5 < T2/T1 < 5$.

2. The sealable sheet according to claim 1, wherein

a ratio of ~~a~~ the recessed amount D2 in ~~an~~ the iron ball drop test of the one-side surface in the thickness direction of the second layer at 90°C to the thickness T2 of the second layer satisfies the formula of $0.1 < D2/T2 < 0.2$.